

P E N D I N G C L A I M S

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (previously amended) An apparatus comprising:

an integrated circuit die;

an integrated circuit package coupled to a first face of the integrated circuit die;

mold compound in contact with the integrated circuit die and the integrated circuit package, the mold compound comprising a face substantially coplanar with a second face of the integrated circuit die; and

an overlayer coupled to the face of the mold compound and to the second face of the integrated circuit die.
2. (original) An apparatus according to Claim 1, further comprising:

underfill material disposed between the integrated circuit die and the integrated circuit package.
3. (original) An apparatus according to Claim 1, wherein the overlayer comprises thermally conductive material.
4. (original) An apparatus according to Claim 1, wherein the overlayer comprises cured die attach film.

5. (original) An apparatus according to Claim 1, wherein the overlayer comprises cured die attach paste.

6. (previously amended) An apparatus comprising:

an integrated circuit package substrate;

a plurality of integrated circuit die, a first face of each of the plurality of integrated circuit die attached to the integrated circuit package substrate; and

mold compound in contact with the plurality of integrated circuit die and the integrated circuit package substrate, the mold compound comprising a face substantially coplanar with a second face of each of the plurality of integrated circuit die; and

an overlayer coupled to the face of the mold compound and to the second face of each of the plurality of integrated circuit die.

7. (original) An apparatus according to Claim 6, further comprising:

underfill material disposed between the first face of each of the plurality of integrated circuit die and the integrated circuit package substrate.

8. (original) An apparatus according to Claim 6, wherein the overlayer comprises thermally conductive material.

9. (original) An apparatus according to Claim 6, wherein the overlayer comprises cured die attach film.

10. (original) An apparatus according to Claim 6, wherein the overlayer comprises cured die attach paste.

11. (previously amended) A method comprising:

placing an overlayer in contact with a face of mold compound and a first face of an integrated circuit die substantially coplanar with the face of the mold compound,

wherein a second face of the integrated circuit die is coupled to an integrated circuit package, and

wherein the mold compound is in contact with the integrated circuit die and the integrated circuit package.

12. (original) A method according to Claim 11, further comprising:

singulating one of the plurality of integrated circuit die and a respective mounting location of the integrated package substrate.

13. (original) A method according to Claim 11, wherein the overlayer comprises thermally conductive material.

14. (original) A method according to Claim 11, wherein the overlayer comprises cured die attach film.

15. (original) A method according to Claim 11, wherein the overlayer comprises cured die attach paste.

16. (previously amended) A system comprising:

a microprocessor comprising:

an integrated circuit die;

an integrated circuit package coupled to a first face of the integrated circuit die;

mold compound in contact with the integrated circuit die and the integrated circuit package, the mold compound comprising a face substantially coplanar with a second face of the integrated circuit die; and

an overlayer coupled to the face of the mold compound and to the second face of the integrated circuit die; and

a double data rate memory electrically coupled to the microprocessor.

17. (original) A system according to Claim 16, wherein the overlayer comprises thermally conductive material.

18. (original) A system according to Claim 16, further comprising:

a motherboard electrically coupled to the microprocessor and to the memory.